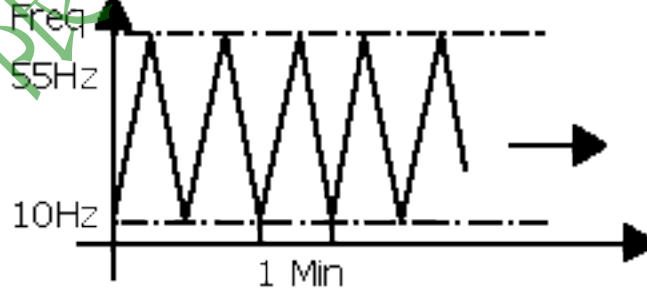

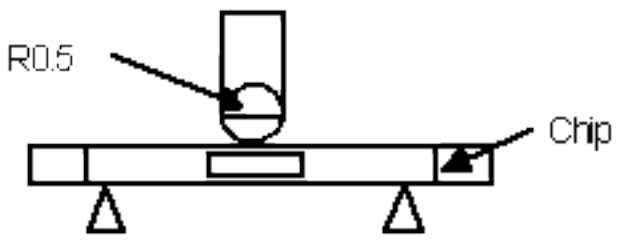


Item(项目)	Required Characteristics(要求)	Test Method / Condition(测试方法)
Solderability test Reference documents: MIL-STD-202G Method 208H IPC J-STD-002C 可焊性试验	Terminals area must have 95% min. Solder coverage 端子必须有95%以上著锡	1. Dip pads in flux then dip in solder pot at $245\pm 5^{\circ}\text{C}$ for 5 seconds. 2. Solder: lead free 3. Flux: rosin flux 1. 端子浸入助焊剂,然后侵入 $245\pm 5^{\circ}\text{C}$ 锡炉中5秒 2. 焊料: 无铅焊料 3. 助焊剂: 松香助焊剂
Heat endurance of Reflow soldering Reference documents: IPC J-STD-020D 过再流焊试验	1. No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ or 15% 3. $\Delta Q/Q \leq 30\%$ 4. $\Delta \text{DCR}/\text{DCR} \leq 10\%$ 1. 无明显的外观缺陷 2. 感值变化不超过10%或者15% 3. 品质因数变化不超过30% 4. 直流电阻变化不超过10%	1. Refer to the next page reflow curve Go through 3 times 2. The peak temperature : $245\pm 5^{\circ}\text{C}$ 1. 参照下页回流焊曲线过三次 2. 峰值温度为: $245\pm 5^{\circ}\text{C}$
Vibration test Reference documents: MIL-STD-202G Method 201A 振动试验	1. No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ 3. $\Delta Q/Q \leq 30\%$ 4. $\Delta \text{DCR}/\text{DCR} \leq 10\%$ 1. 无明显的外观缺陷 2. 感值变化不超过10% 3. 品质因数变化不超过30% 4. 直流电阻变化不超过10%	Apply frequency 10~55Hz. 1.55mm amplitude in each of perpendicular direction for 2 hours.(total 6 hours)  用10~55Hz 振动频率1.55mm振幅沿X, Y, Z方向各振动2小时(共6小时)
Drop test Reference documents: MIL-STD-202G Method 203C 落下试验	1. No case deformation or change in appearance. 2. $\Delta L/L \leq 10\%$ 3. $\Delta Q/Q \leq 30\%$ 4. $\Delta \text{DCR}/\text{DCR} \leq 10\%$ 1. 无明显的外观缺陷 2. 感值变化不超过10% 3. 品质因数变化不超过30% 4. 直流电阻变化不超过10%	Packaged & Drop down from 1m with $981\text{m/s}^2(100\text{G})$ attitude In 1 angle 1 ridges & 2 surfaces orientations. 将产品包装从1米高度自然落下至试验板上 1角1棱2面
Terminal strength push test Reference documents: JIS C 5321:1997 端子强度试验	Pulling test: Define: A: sectional area of terminal $0.5\text{mm}^2 < A \leq 1.2\text{mm}^2$ force $\geq 20\text{N}$ time: 10sec $1.2\text{mm}^2 < A$ force $\geq 40\text{N}$ time: 10sec Bending test: Soldering the products on PCB, after the pulling test and bending test, terminal should not pull off 推力测试: 定义: A: 焊接端子截面积 $0.5\text{mm}^2 < A \leq 1.2\text{mm}^2$ 推力 $\geq 20\text{N}$ 时间: 10S $1.2\text{mm}^2 < A$ 推力 $\geq 40\text{N}$ 时间: 10S 弯折测试: 将产品焊于PCB上, 分别经过推力测试和弯折测试后, 端子不会发生松脱	Bend the testing PCB at middle point, the deflection shall be 2mm   Bending test 将PCB对中弯折到达挠度2mm
Resistance to solvent test Reference documents: IEC 68-2-45:1993 耐溶剂性试验	No case deformation or change in appearance, or obliteration of marking 无外观破坏及标记破坏	To dip parts into IPA solvent for $5\pm 0.5\text{Min}$, then drying them at room temp for 5Min, at last, to brushing marking 10 times. 在IPA溶剂中浸泡 5 ± 0.5 分钟, 室温下干燥5分钟然后擦拭10次.